Overview
To meet the demand for smaller footprints, improved electrical performance and/or higher input/output in a given space, manufacturers are investigating advanced packaging technologies. This course will allow students to make informed decisions about advanced packaging technologies (flip chips, chip scale packages, wire bonding, micro BGAs and BGAs) based upon companies’ needs.

Who Should Attend
Engineering and manufacturing managers, process engineers, technicians, machine operators and trainers responsible for making next-generation manufacturing decisions in the company.

Content
• Basic overview of die fabrication and chip scale packages
• Inspection technologies
• Production implementation of flip chip and chip scale processes, including BGA and micro BGA
• Rework processes
• Underfill/encapsulation
• Uses of advanced packages and manufacturing assemblies in today’s market
• Wire bonding and die placement techniques

Benefits
Receive hands-on training on advanced packaging equipment located at the ACI demonstration factory. Identify and perform critical process steps when manufacturing BGAs, micro BGAs, flip chips and chip scale packages. Learn to identify and implement process control methods and practices when manufacturing assemblies with advanced packages.

Duration, Registration and Pricing
Contact the training center via any of the methods provided below for pricing of this three-day course.